



Product Change Notification - SYST-19CBMJ373

Date:

22 Jul 2019

Product Category:

P-Channel Enhancement Mode MOSFETs

Affected CPNs:**Notification subject:**

Data Sheet - TP0604 P-Channel Enhancement-Mode Vertical DMOS FET Data Sheet

Notification text:

SYST-19CBMJ373

Microchip has released a new DeviceDoc for the TP0604 P-Channel Enhancement-Mode Vertical DMOS FET Data Sheet of devices. If you are using one of these read the document located [TP0604 P-Channel Enhancement-Mode Vertical DMOS FET Data Sheet](#).

Notification Status: Final

Description of Change:

- 1) Converted Supertex Doc# DSFP-TP0604 to Microchip DS20005956A
- 2) Changed the package marking format
- 3) Added a pin function table
- 4) Removed the TO-92 P002, P003, P005, P013 and P014 media types
- 5) Made minor text changes throughout the document

Impacts to Data Sheet: None

Reason for Change: To Improve Manufacturability

Change Implementation Status: Complete

Date Document Changes Effective: 22 Jul 2019

NOTE: Please be advised that this is a change to the document only the product has not been changed.

Markings to Distinguish Revised from Unrevised Devices: N/A

Attachment(s):

[TP0604 P-Channel Enhancement-Mode Vertical DMOS FET Data Sheet](#)

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Affected Catalog Part Numbers (CPN)

TP0604N3-G

P-Channel Enhancement-Mode Vertical DMOS FET

Features

- -2.4V Maximum Low Threshold
- High Input Impedance
- Low Input Capacitance (95 pF)
- Fast Switching Speeds
- Low On-Resistance
- Free from Secondary Breakdown
- Low Input and Output Leakage

Applications

- Logic-Level Interfaces (Ideal for TTL and CMOS)
- Solid-State Relays
- Battery-Operated Systems
- Photovoltaic Drives
- Analog Switches
- General Purpose Line Drivers
- Telecommunication Switches

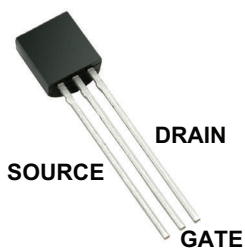
General Description

The TP0604 low-threshold, Enhancement-mode (normally-off) transistor uses a vertical DMOS structure and a well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally induced secondary breakdown.

Microchip's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance and fast switching speeds are desired.

Package Type

3-lead TO-92
(Top view)



See [Table 3-1](#) for pin information.

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Drain-to-Source Voltage	BV_{DSS}
Drain-to-Gate Voltage	BV_{DGS}
Gate-to-Source Voltage	$\pm 20V$
Operating Ambient Temperature, T_A	$-55^{\circ}C$ to $+150^{\circ}C$
Storage Temperature, T_S	$-55^{\circ}C$ to $+150^{\circ}C$

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $T_A = 25^{\circ}C$ unless otherwise specified. All DC parameters are 100% tested at $25^{\circ}C$ unless otherwise stated. Pulse test: 300 μs pulse, 2% duty cycle

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Drain-to-Source Breakdown Voltage	BV_{DSS}	-40	—	—	V	$V_{GS} = 0V$, $I_D = -2$ mA
Gate Threshold Voltage	$V_{GS(th)}$	-1	—	-2.4	V	$V_{GS} = V_{DS}$, $I_D = -1$ mA
Change in $V_{GS(th)}$ with Temperature	$\Delta V_{GS(th)}$	—	-3	-4.5	mV/ $^{\circ}C$	$V_{GS} = V_{DS}$, $I_D = -1$ mA (Note 1)
Gate Body Leakage Current	I_{GSS}	—	—	-100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$
Zero-Gate Voltage Drain Current	I_{DSS}	—	—	-10	μA	$V_{GS} = 0V$, $V_{DS} =$ Maximum rating
		—	—	-1	mA	$V_{DS} = 0.8$ Maximum rating, $V_{GS} = 0V$, $T_A = 125^{\circ}C$ (Note 1)
On-State Drain Current	$I_{D(ON)}$	-0.4	-0.6	—	A	$V_{GS} = -5V$, $V_{DS} = -20V$
		-2	-3.3	—	A	$V_{GS} = -10V$, $V_{DS} = -20V$
Static Drain-to-Source On-State Resistance	$R_{DS(ON)}$	—	2	3.5	Ω	$V_{GS} = -5V$, $I_D = -250$ mA
		—	1.5	2	Ω	$V_{GS} = -10V$, $I_D = -1A$
Change in $R_{DS(ON)}$ with Temperature	$\Delta R_{DS(ON)}$	—	—	1.2	%/ $^{\circ}C$	$V_{GS} = -10V$, $I_D = -1A$ (Note 1)

Note 1: Specification is obtained by characterization and is not 100% tested.

AC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $T_A = 25^\circ\text{C}$ unless otherwise specified. Specification is obtained by characterization and is not 100% tested.

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Forward Transconductance	G_{FS}	400	600	—	mmho	$V_{DS} = -20V, I_D = -1A$
Input Capacitance	C_{ISS}	—	95	150	pF	$V_{GS} = 0V,$ $V_{DS} = -20V,$ $f = 1\text{ MHz}$
Common Source Output Capacitance	C_{OSS}	—	85	120	pF	
Reverse Transfer Capacitance	C_{RSS}	—	35	60	pF	
Turn-On Delay Time	$t_{d(ON)}$	—	5	8	ns	$V_{DD} = -20V,$ $I_D = -1A,$ $R_{GEN} = 25\Omega$
Rise Time	t_r	—	7	18	ns	
Turn-Off Delay Time	$t_{d(OFF)}$	—	10	15	ns	
Fall Time	t_f	—	6	19	ns	
DIODE PARAMETER						
Diode Forward Voltage Drop	V_{SD}	—	-1.3	-2	V	$V_{GS} = 0V, I_{SD} = -1.5A$ (Note 1)
Reverse Recovery Time	t_{rr}	—	300	—	ns	$V_{GS} = 0V, I_{SD} = -1.5A$

Note 1: Unless otherwise stated, all DC parameters are 100% tested at 25°C .
Pulse test: 300 μs pulse, 2% duty cycle

TEMPERATURE SPECIFICATIONS

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
TEMPERATURE RANGE						
Operating Ambient Temperature	T_A	-55	—	+150	$^\circ\text{C}$	
Storage Temperature	T_S	-55	—	+150	$^\circ\text{C}$	
PACKAGE THERMAL RESISTANCE						
3-lead TO-92	θ_{JA}	—	132	—	$^\circ\text{C/W}$	

THERMAL CHARACTERISTICS

Package	I_D (Note 1) (Continuous) (A)	I_D (Pulsed) (A)	Power Dissipation at $T_A = 25^\circ\text{C}$ (W)	I_{DR} (Note 1) (mA)	I_{DRM} (A)
3-lead TO-92	-0.43	-0.42	0.74	-0.43	-4.2

Note 1: I_D (continuous) is limited by maximum rated T_J .

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g. outside specified power supply range) and therefore outside the warranted range.

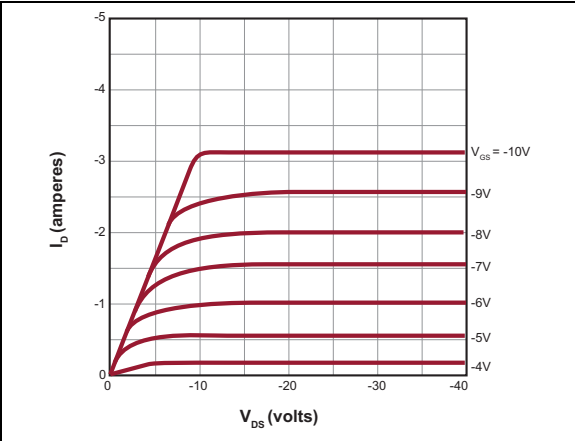


FIGURE 2-1: Output Characteristics.

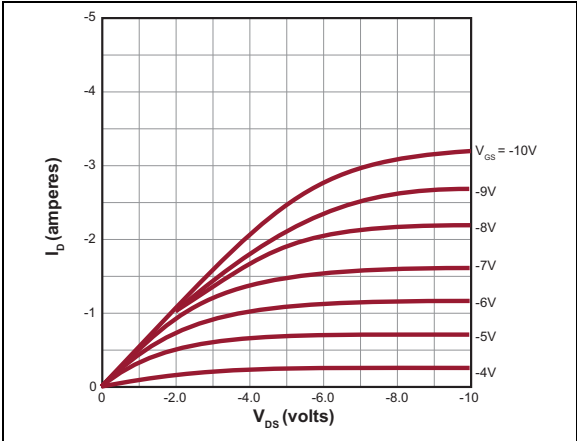


FIGURE 2-4: Saturation Characteristics.

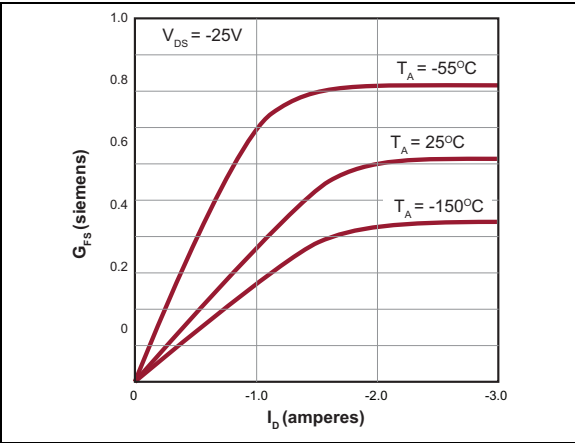


FIGURE 2-2: Transconductance vs. Drain Current.

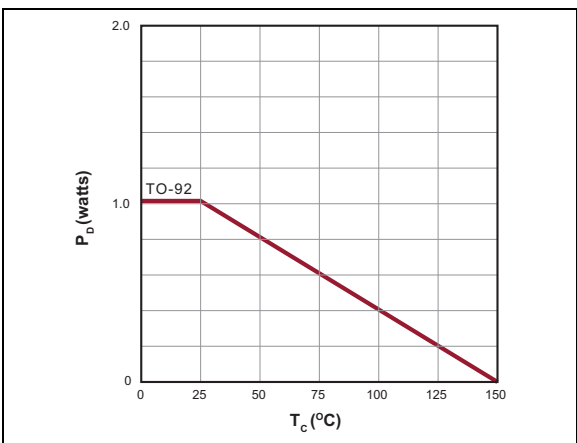


FIGURE 2-5: Power Dissipation vs. Case Temperature.

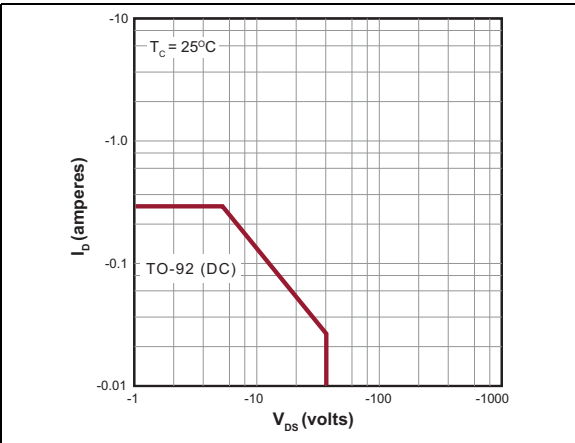


FIGURE 2-3: Maximum Rated Safe Operating Area.

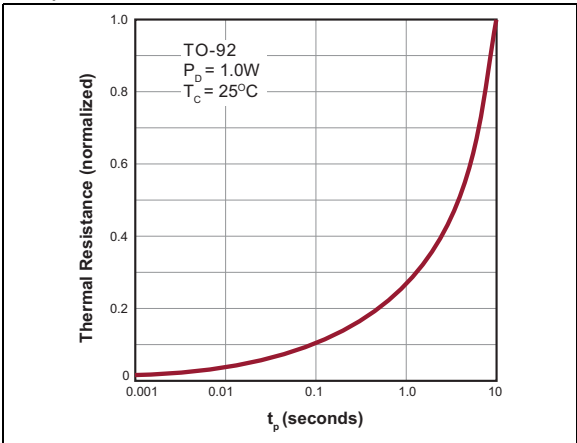


FIGURE 2-6: Thermal Response Characteristics.

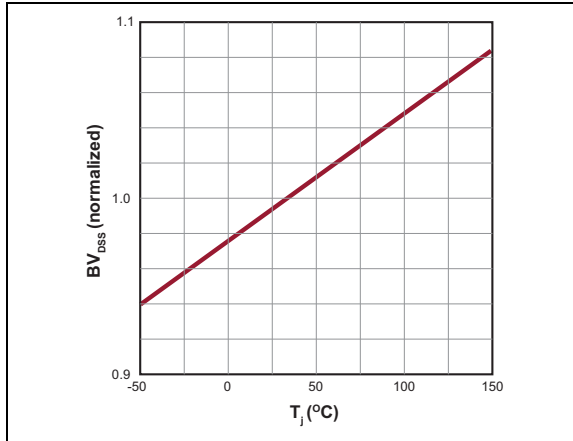


FIGURE 2-7: BV_{DSS} Variation with Temperature.

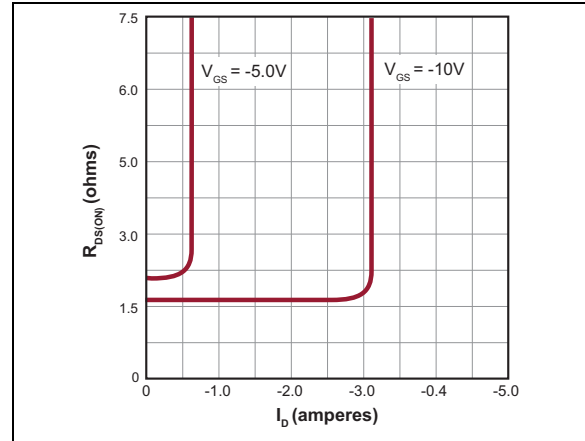


FIGURE 2-10: On-Resistance vs. Drain Current.

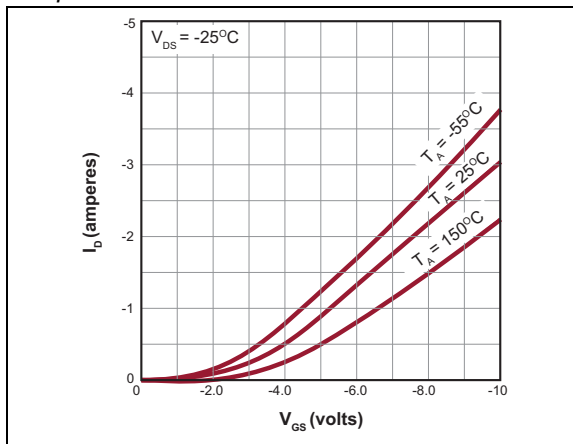


FIGURE 2-8: Transfer Characteristics.

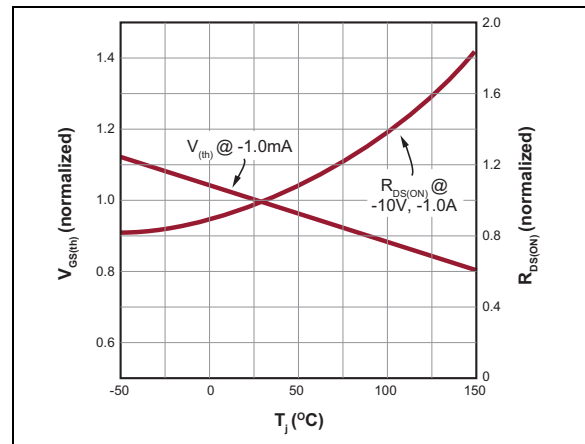


FIGURE 2-11: V_{th} and R_{DS} Variation with Temperature.

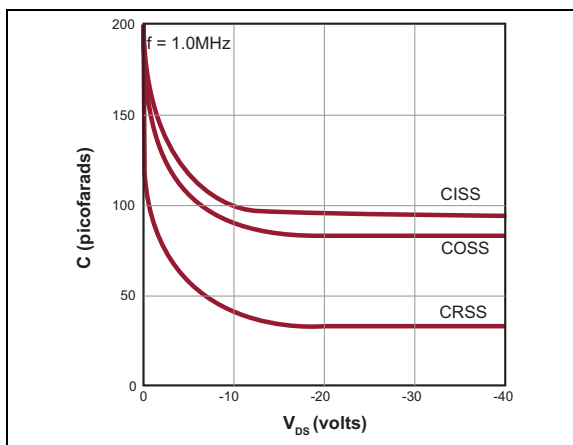


FIGURE 2-9: Capacitance vs. Drain-to-Source Voltage.

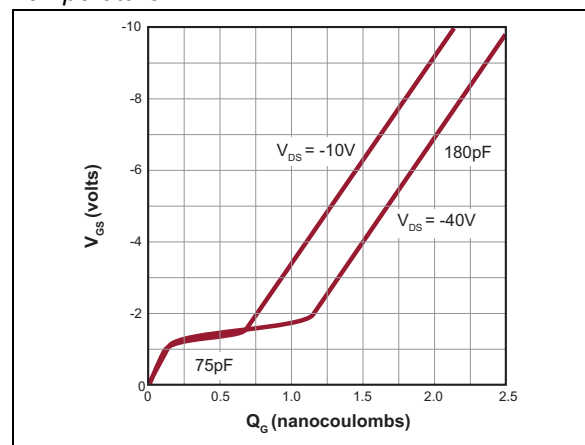


FIGURE 2-12: Gate Drive Dynamic Characteristics.

3.0 PIN DESCRIPTION

The details on the pins of TP0604 are listed in [Table 3-1](#). Refer to [Package Type](#) for the location of pins.

TABLE 3-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	Source	Source
2	Gate	Gate
3	Drain	Drain

4.0 FUNCTIONAL DESCRIPTION

Figure 4-1 illustrates the switching waveforms and test circuit for TP0604.

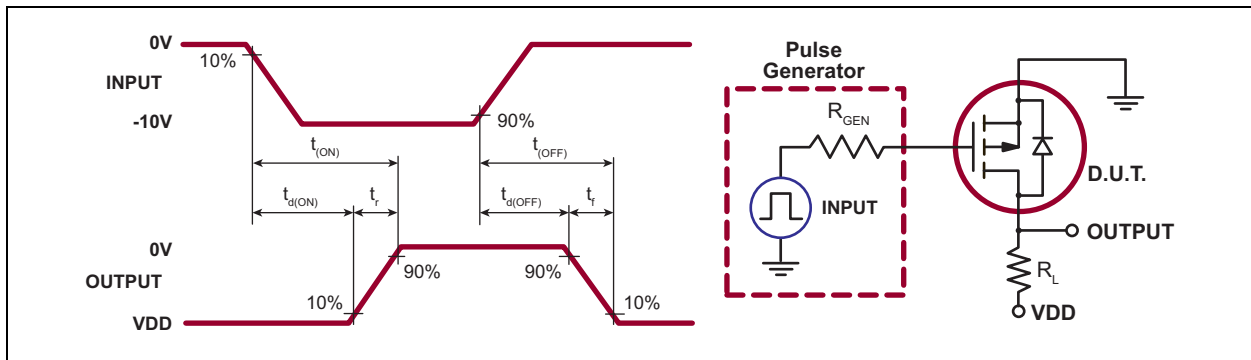


FIGURE 4-1: Switching Waveforms and Test Circuit.

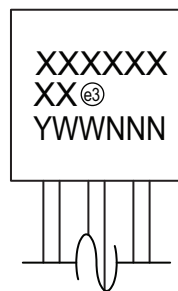
TABLE 4-1: PRODUCT SUMMARY

BV_{DSS}/BV_{DGS} (V)	$R_{DS(ON)}$ (Maximum) (Ω)	$I_{D(ON)}$ (Minimum) (A)	$V_{GS(TH)}$ (Maximum) (V)
-40	2	-2	-2.4

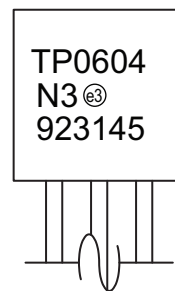
5.0 PACKAGING INFORMATION

5.1 Package Marking Information

3-lead TO-92



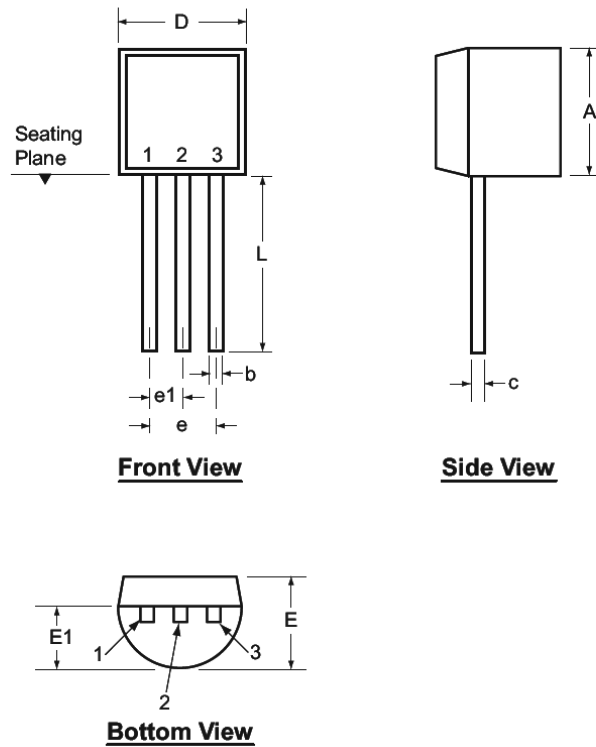
Example



Legend:	XX...X	Product Code or Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC [®] designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.

3-Lead TO-92 Package Outline (L/LL/N3)



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Symbol		A	b	c	D	E	E1	e	e1	L
Dimensions (inches)	MIN	.170	.014 [†]	.014 [†]	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022 [†]	.022 [†]	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

* This dimension is not specified in the JEDEC drawing.

† This dimension differs from the JEDEC drawing.

Drawings not to scale.

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (July 2019)

- Converted Supertex Doc# DSFP-TP0604 to Microchip DS20005956A
- Changed the package marking format
- Added a pin function table
- Removed the TO-92 P002, P003, P005, P013 and P014 media types
- Made minor text changes throughout the document

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